



## DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name. I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **Thermal Microvalves**, the specification of which was filed on **03/02/00** as Application Serial No. **09/517,680**. I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

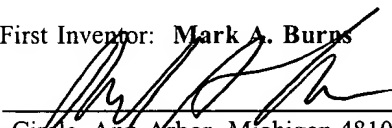
I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>08/888,309</u>	<u>7/03/1997</u>	<u>Patented</u>
<i>Application Serial No.</i>	<i>Filing Date</i>	<i>Patented, Pending or Abandoned</i>
<u>08/529,293</u>	<u>9/15/1995</u>	<u>Abandoned</u>
<i>Application Serial No.</i>	<i>Filing Date</i>	<i>Patented, Pending or Abandoned</i>

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under § 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole or First Inventor: **Mark A. Burns**

Inventor's Signature: 

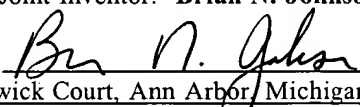
Residence: 639 Trego Circle, Ann Arbor, Michigan 48105

Post Office Address: 639 Trego Circle, Ann Arbor, Michigan 48105

Date: 6/21/00

Citizenship: United States of America

Full Name of Second Joint Inventor: **Brian N. Johnson**

Inventor's Signature: 

Residence: 2648 Fenwick Court, Ann Arbor, Michigan 48105

Post Office Address: 2648 Fenwick Court, Ann Arbor, Michigan 48105

Date: 6/21/00

Citizenship: United States of America

Full Name of Third Joint Inventor: **Michael Chen**

Inventor's Signature: \_\_\_\_\_

Residence: 26 Tosca Street, Singapore 455465, Singapore

Post Office Address: 26 Tosca Street, Singapore 455465, Singapore

Date: \_\_\_\_\_

Citizenship: United States of America



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Full Name of Sole or First Inventor: **Mark A. Burns**

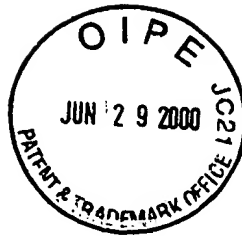
Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Residence: 639 Trego Circle, Ann Arbor, Michigan 48105 Citizenship: United States of America  
Post Office Address: 639 Trego Circle, Ann Arbor, Michigan 48105

Full Name of Second Joint Inventor: **Brian N. Johnson**

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Residence: 2648 Fenwick Court, Ann Arbor, Michigan 48105 Citizenship: United States of America  
Post Office Address: 2648 Fenwick Court, Ann Arbor, Michigan 48105

Full Name of Third Joint Inventor: **Michael Chen**

Inventor's Signature: Michael Chen Date: 27 May '00  
Residence: 26 Tosca Street, Singapore 455465, Singapore Citizenship: United States of America  
Post Office Address: 26 Tosca Street, Singapore 455465, Singapore



Applicant / Patentee: Mark A. Burns *et al.*  
Serial No.: 09/517,680  
Filed: 03/02/00  
For: Thermal Microvalves

**VERIFIED STATEMENT (DECLARATION) CLAIMING SMALL ENTITY STATUS  
(37 CFR §§ 1.9(f) and 1.27(d) - NONPROFIT ORGANIZATION)**

I hereby declare that I am an official empowered to act on behalf of the university (or other institution of higher education) identified below:

THE REGENTS OF THE UNIVERSITY OF MICHIGAN  
3003 South State Street  
Ann Arbor, Michigan 48109-1280

I hereby declare that the nonprofit organization identified above qualifies as a nonprofit organization as defined in 37 CFR § 1.9(e) for purposes of paying reduced fees under §§ 41(a) and (b) of Title 35, United States Code with regard to the invention entitled **Thermal Microvalves**, by inventors named **Mark A. Burns *et al.***, described in Application Serial No. 09/517,680, filed 03/02/00.

I hereby declare that rights under contract or law have been conveyed to and remain with the nonprofit organization with regard to the above identified invention.

I acknowledge the duty to file, in this application or patent, notification of any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR § 1.28(b)).

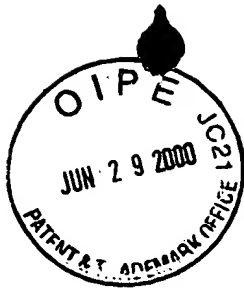
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.

Date: 06-22-00

By: Marvin G. Parnes

Name: MARVIN G. PARNES

Title: Associate Vice President for Research  
Interim Director, Technology Management Office



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Mark A. Burns *et al.*  
Serial No.: 09/517,680  
Filed: 03/02/00  
Entitled: Thermal Microvalves

Group No.: 1743  
Examiner:

POWER OF ATTORNEY BY ASSIGNEE

Assistant Commissioner for Patents  
Washington, D.C. 20231  
3353

THE REGENTS OF THE UNIVERSITY OF MICHIGAN, as Assignee of record of the entire interest of the above-identified patent application, hereby appoints the members of the firm of MEDLEN & CARROLL, LLP, a firm composed of:

Virginia S. Medlen	(Reg. No. 32,050)	J. Mitchell Jones	(Reg. No. 44,174)
Peter G. Carroll	(Reg. No. 32,837)	David J. Wilson	(Reg. No. 45,225)
Kamrin T. MacKnight	(Reg. No. 38,230)	Jason R. Bond	(Reg. No. P-45,439)
David A. Casimir	(Reg. No. 42,395)	Emily C. Tongco	(Reg. No. P-46,473)
Maha A. Hamdan	(Reg. No. 43,655)		

as its attorneys with full power of substitution to prosecute this application and transact all business in the Patent and Trademark Office in connection therewith.

Please direct all future correspondence and telephone calls regarding this application to:

Peter G. Carroll  
MEDLEN & CARROLL, LLP  
220 Montgomery Street, Suite 2200  
San Francisco, California 94104  
Telephone: 617/252-3353  
Facsimile: 617/252-3323

I hereby certify that the Assignment document filed with the application or filed subsequent to the filing date of the application, has been reviewed and I hereby certify that, to the best of my knowledge and belief, title is with THE REGENTS OF THE UNIVERSITY OF MICHIGAN.

Dated: 06-22-00

By: Marvin G. Parnes

Name: MARVIN G. PARNES

Title: Associate Vice President for Research  
Interim Director, Technology Management Office

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